

## P-Channel Enhancement Mode Power MOSFET

### Description

The PT H6UÍ I uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

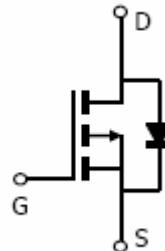
### General Features

- $V_{DS} = -55V, I_D = -30A$
- $R_{DS(ON)} < 40m\Omega @ V_{GS} = -10V$
- High density cell design for ultra low  $R_{DS(on)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

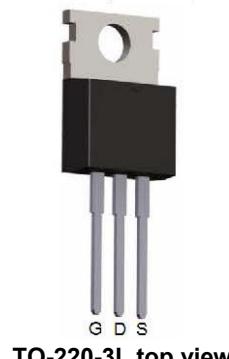
**100% UIS TESTED!**



Schematic diagram



Marking and pin assignment



TO-220-3L top view

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
PT H6UÍ I	PT H6UÍ I	TO-220-3L	-	-	-

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-55	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	-30	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	-21	A
Pulsed Drain Current	$I_{DM}$	110	A
Maximum Power Dissipation	$P_D$	90	W
Derating factor		0.72	W/ $^\circ C$
Single pulse avalanche energy (Note 5)	$E_{AS}$	420	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	$^\circ C$

### Thermal Characteristic

Thermal Resistance,Junction-to-Case(Note 2)	R <sub>θJC</sub>	1.39	°C/W
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### Electrical Characteristics ( $T_c=25^\circ\text{C}$ unless otherwise noted)

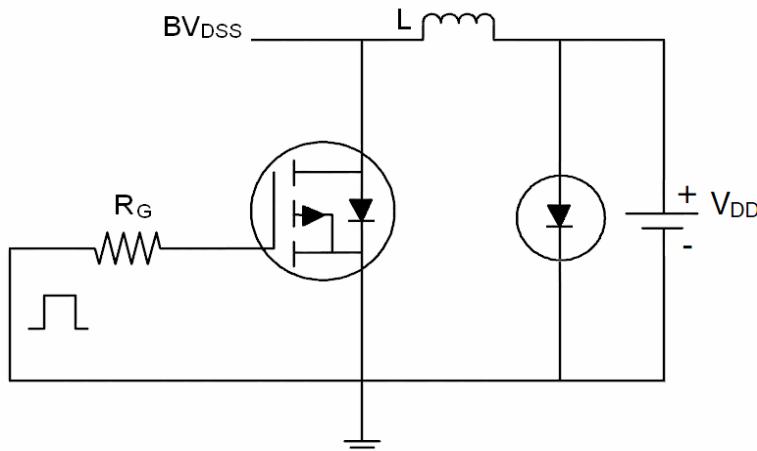
Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-55	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-55V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-2	-2.6	-4	V
Drain-Source On-State Resistance	R <sub>DSON</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-15A	-	30	40	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-25V, I <sub>D</sub> =-16A	8	-	-	S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, F=1.0MHz	-	3500	-	PF
Output Capacitance	C <sub>oss</sub>		-	240	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	153	-	PF
<b>Switching Characteristics (Note 4)</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-30V, I <sub>D</sub> =-15A V <sub>GS</sub> =-10V, R <sub>GEN</sub> =3Ω	-	12	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	15	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	38	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	15	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-44V, I <sub>D</sub> =-16A, V <sub>GS</sub> =-10V	-	56	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	11	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	24	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-24A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	-30	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, IF = -15A di/dt = 100A/μs(Note3)	-	-	71	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	-	170	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

### Notes:

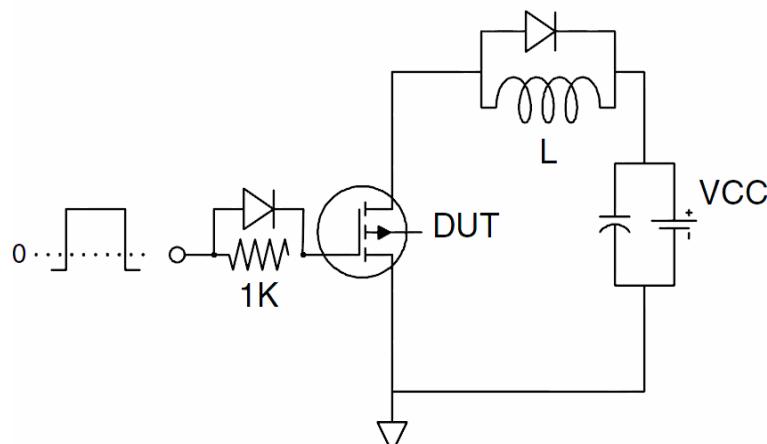
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. E<sub>AS</sub> condition: T<sub>j</sub>=25°C, V<sub>DD</sub>=-25V, V<sub>G</sub>=-20V, L=1mH, R<sub>g</sub>=25Ω, I<sub>AS</sub>=29A

### Test Circuit

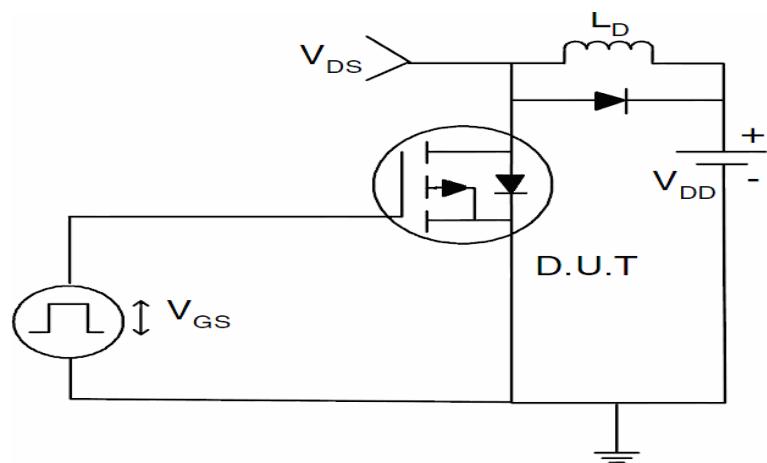
#### 1) E<sub>AS</sub> Test Circuit



#### 2) Gate Charge Test Circuit



#### 3) Switch Time Test Circuit



### Typical Electrical and Thermal Characteristics (Curves)

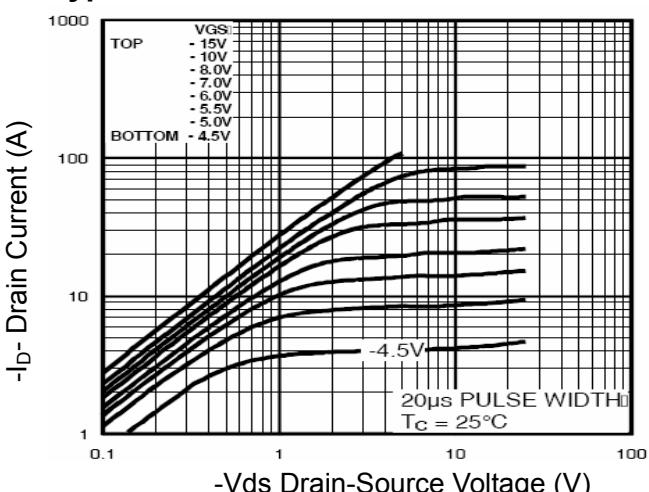


Figure 1 Output Characteristics

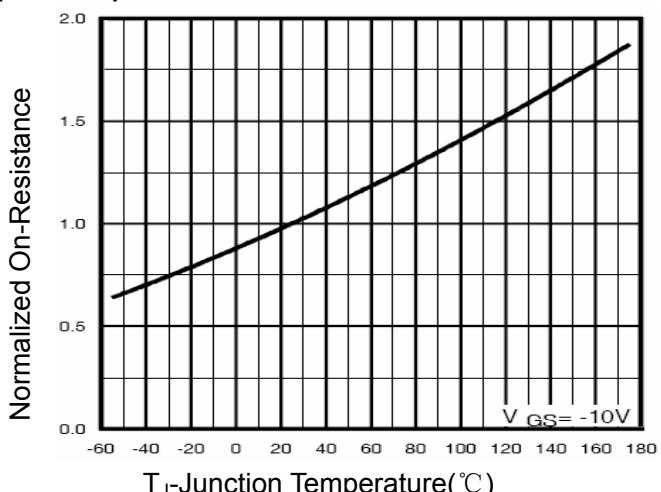


Figure 4 Rdson-JunctionTemperature

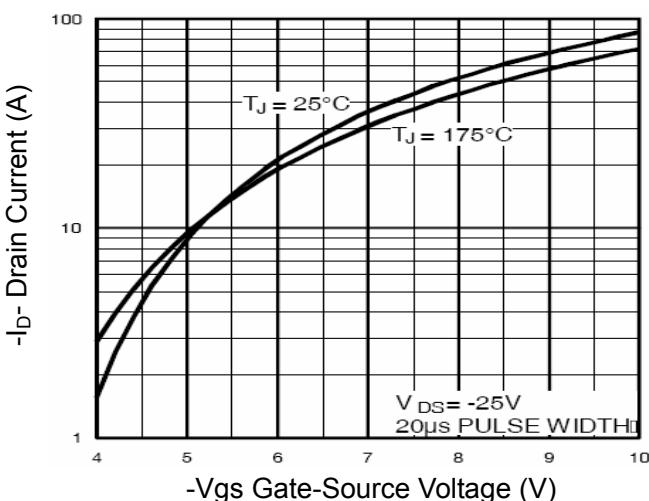


Figure 2 Transfer Characteristics

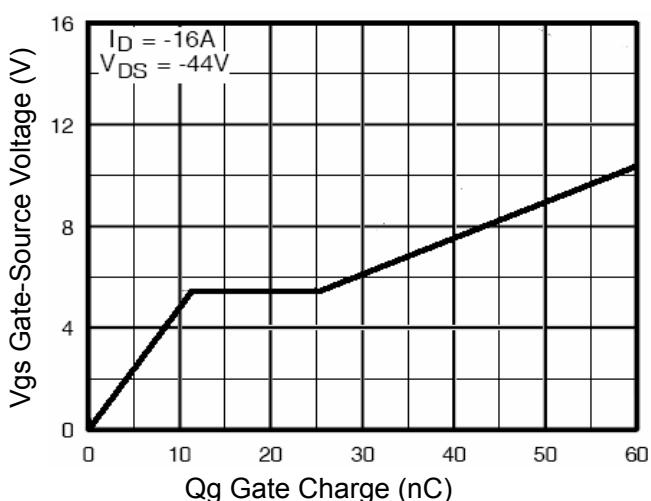


Figure 5 Gate Charge

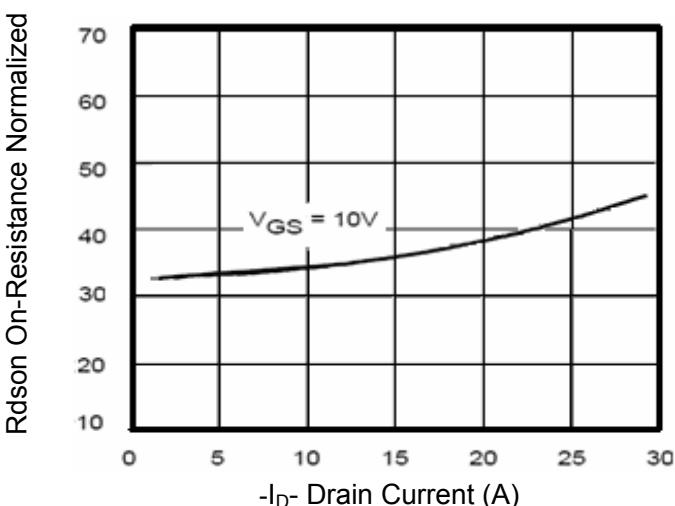


Figure 3 Rdson- Drain Current

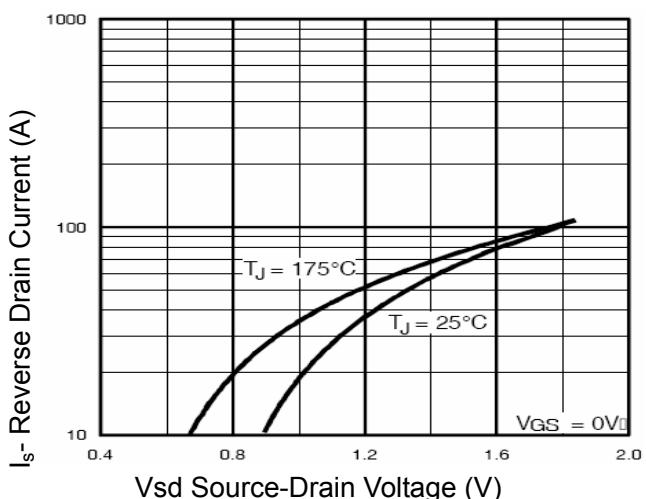


Figure 6 Source- Drain Diode Forward

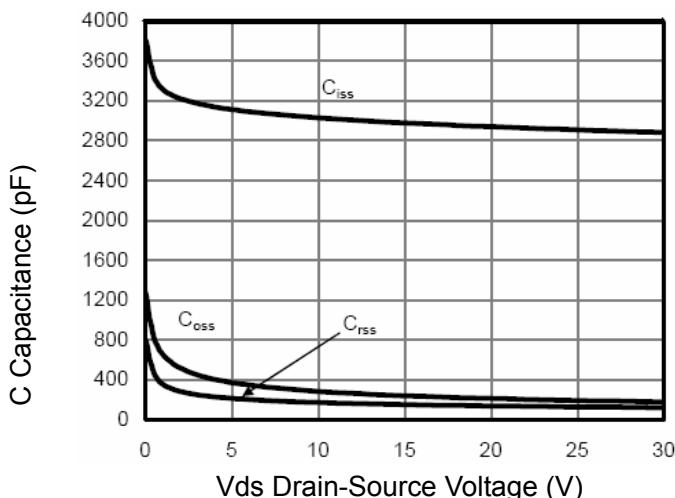


Figure 7 Capacitance vs Vds

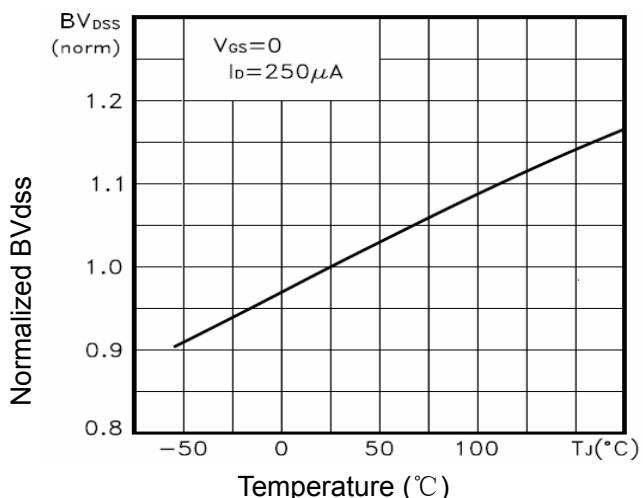


Figure 9 BV<sub>dss</sub> vs Junction Temperature

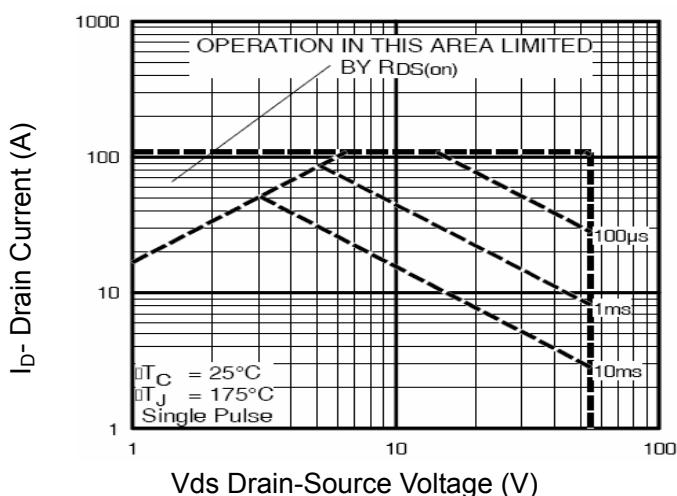


Figure 8 Safe Operation Area

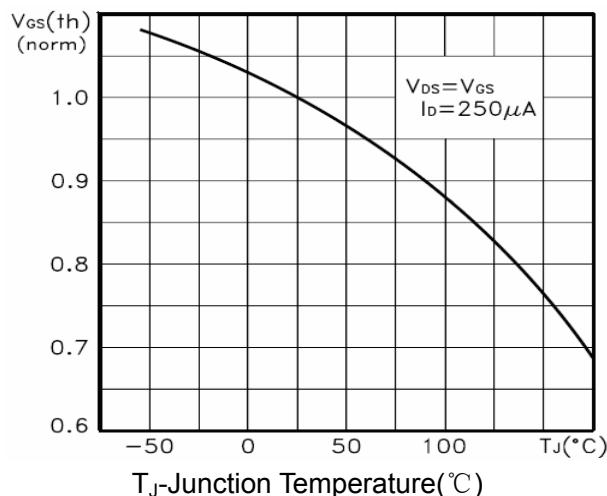


Figure 10 V<sub>Gs(th)</sub> vs Junction Temperature

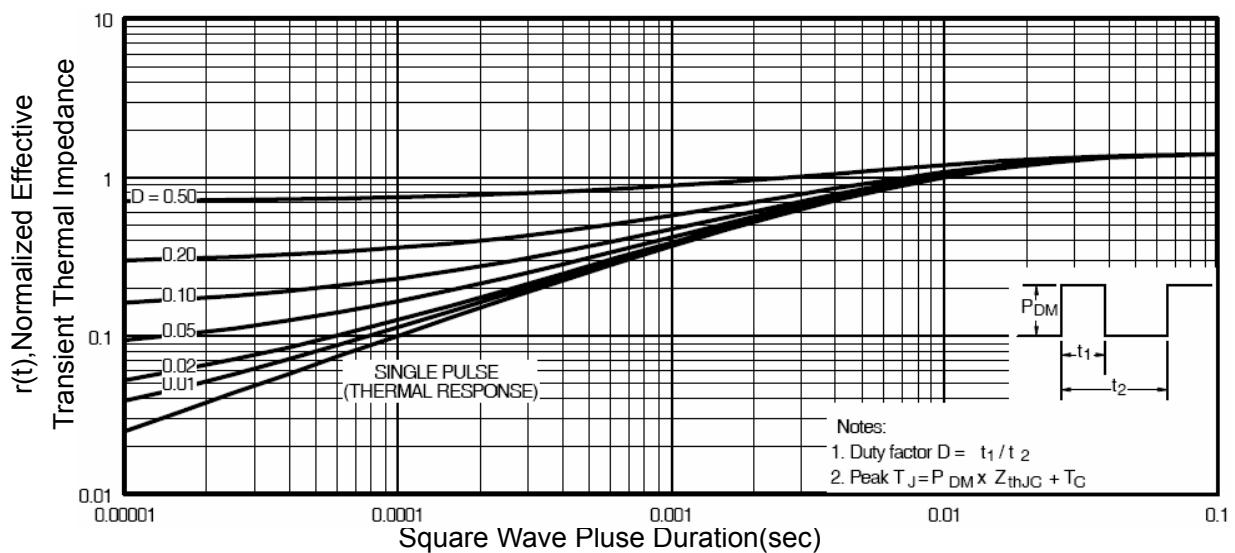
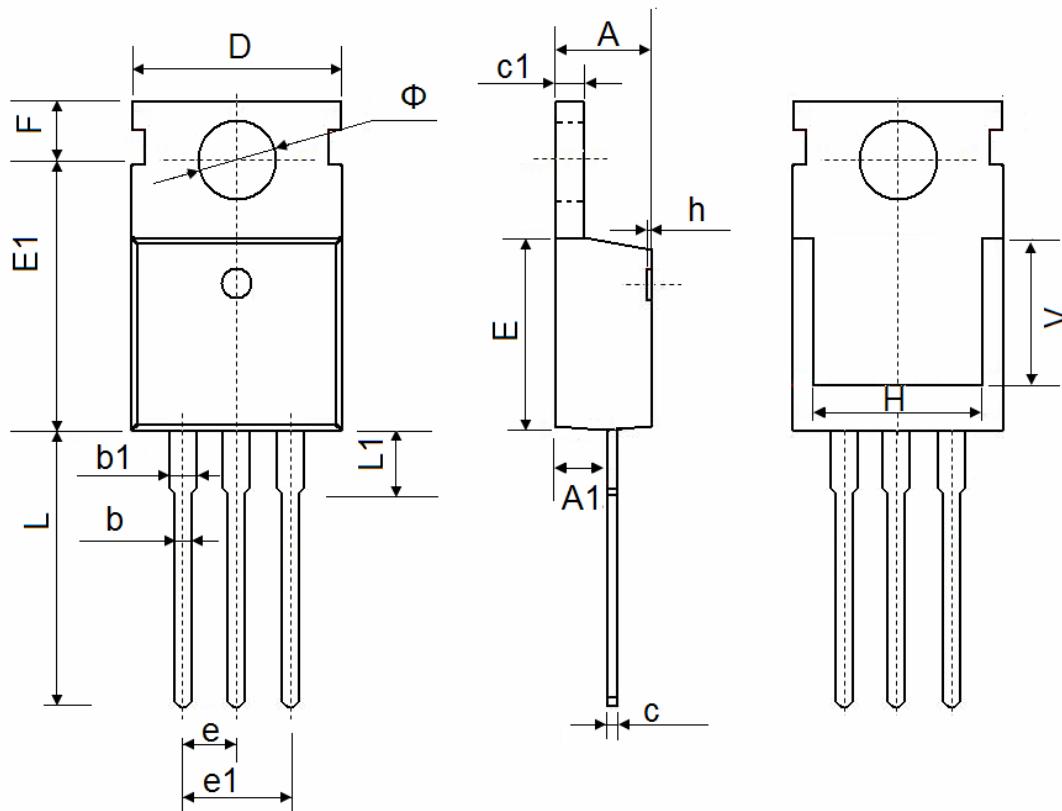


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.134	0.150